

# *Developing IoT Hardware ?*

How to **Fail Fast**  
(or, Make it Fly!)

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[zoidlabs.com](http://zoidlabs.com)

# ***“Fail”? “Fast”?? What???***

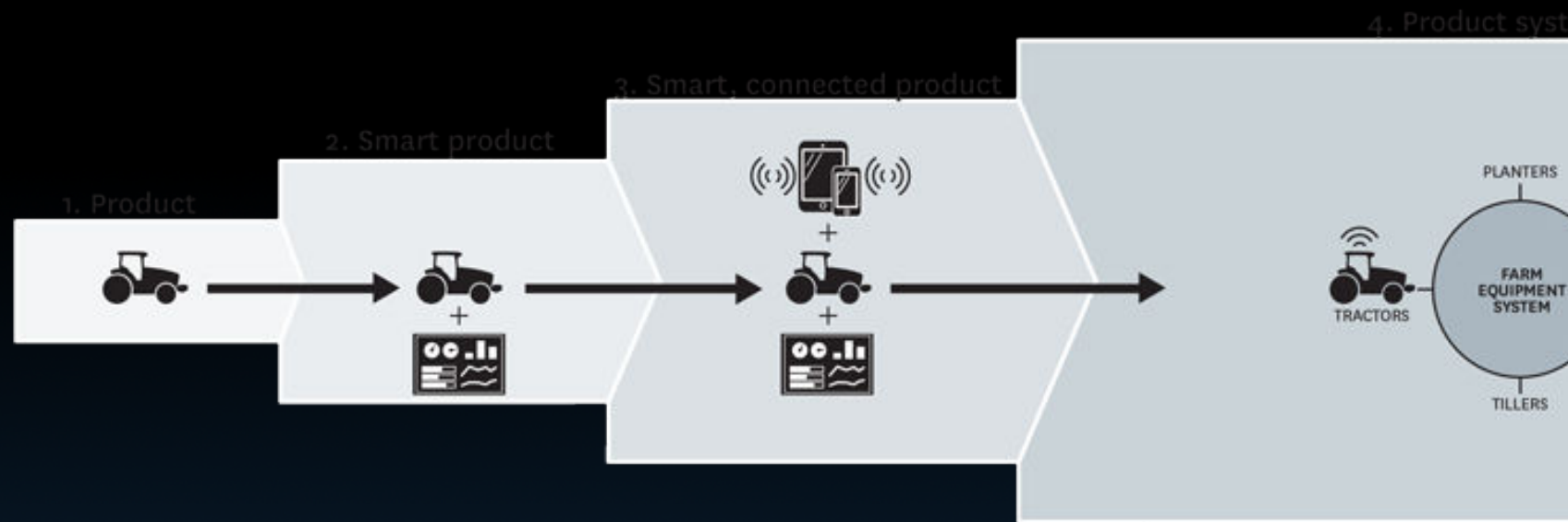
*“The prototype device of XXXX is as big as a standard hardback book, and will cost \$2000 a test when it hits the market. ... The company’s aim is to shrink it down to the size of a mobile phone, with a similar reduction in price.”*

(Source: An actual news report)

# ***What is in my talk***

- Introduction
- IoT H/W Dev Strategy, Step by Step
- DFP (Design for Ease of Prototyping)
- Key risks in Prototyping & Testing
- How to navigate: Strategy, Process, Tools

# *Evolution of Products*



(Source: Harvard Business Review)

# Evolution of Products



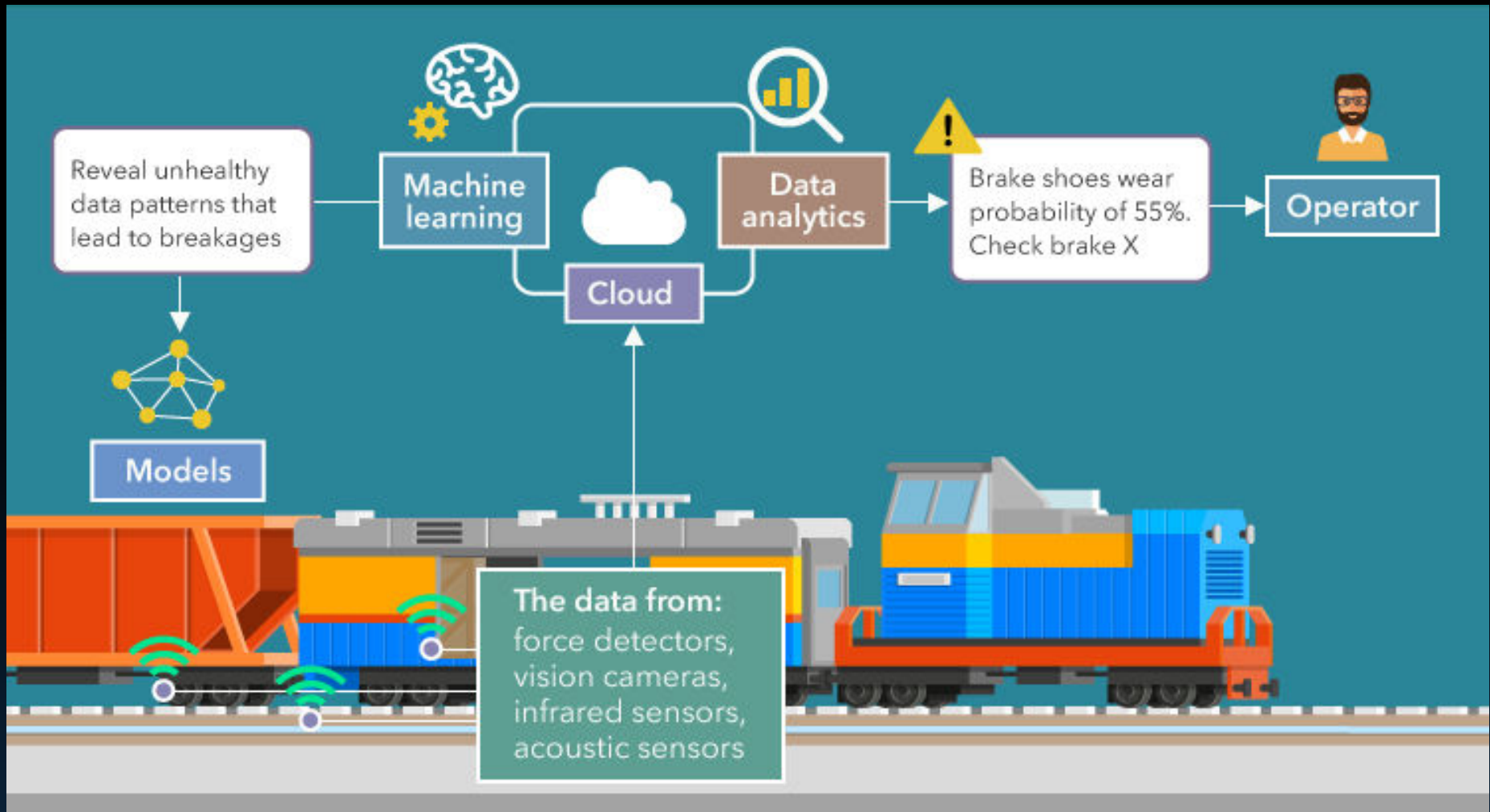
(Source: Harvard Business Review)

# ***Verticals Touched by IoT***

- Smart cities
- Healthcare
- Manufacturing
- Logistics
- Energy & Utilities
- Oil & Gas
- Agriculture
- Home Appliances
- Banking and Insurance
- Physical Security
- ...etc



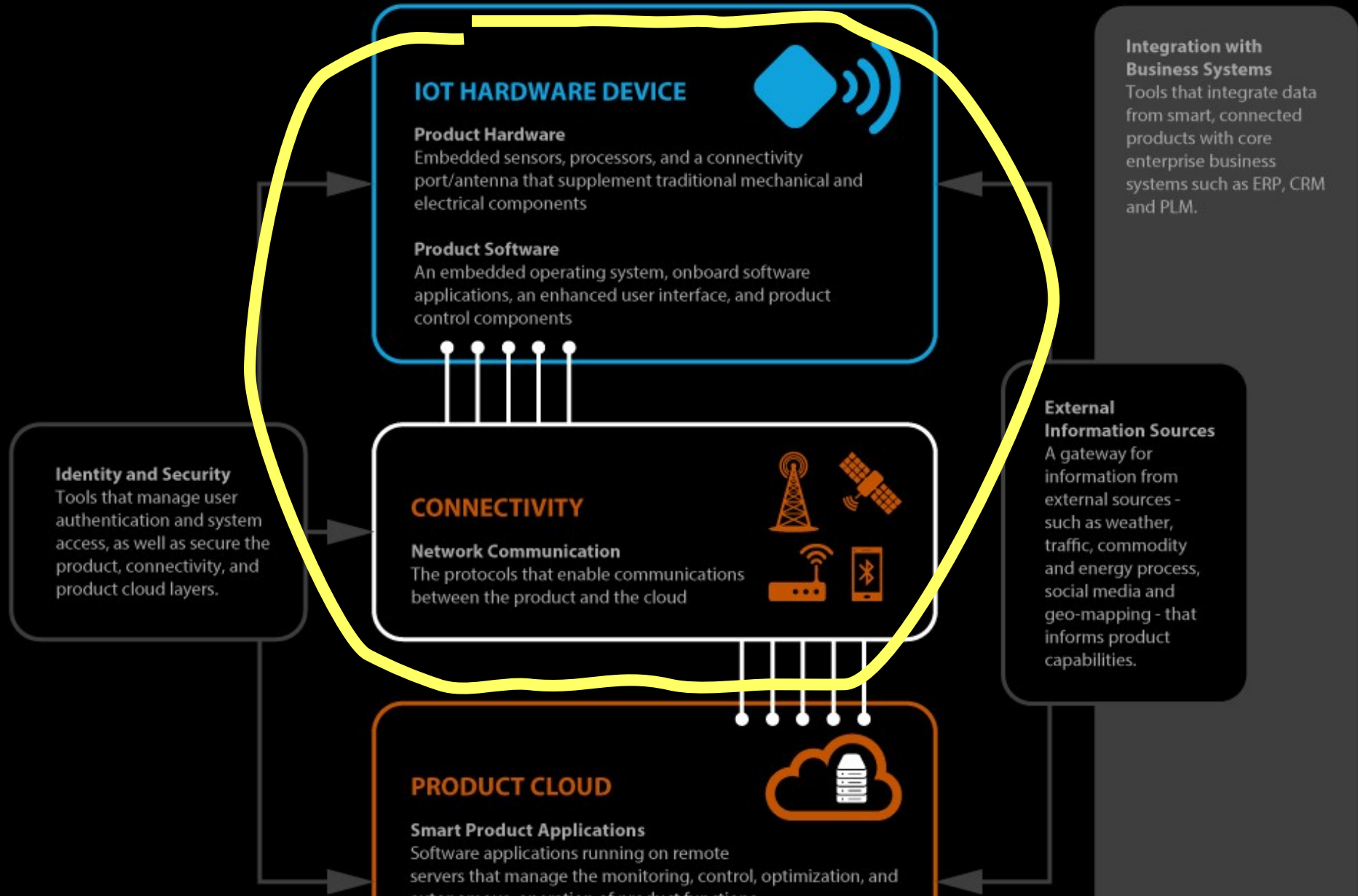
# An Example



Predictive Maintenance in Railways.

Source: ScienceSoft

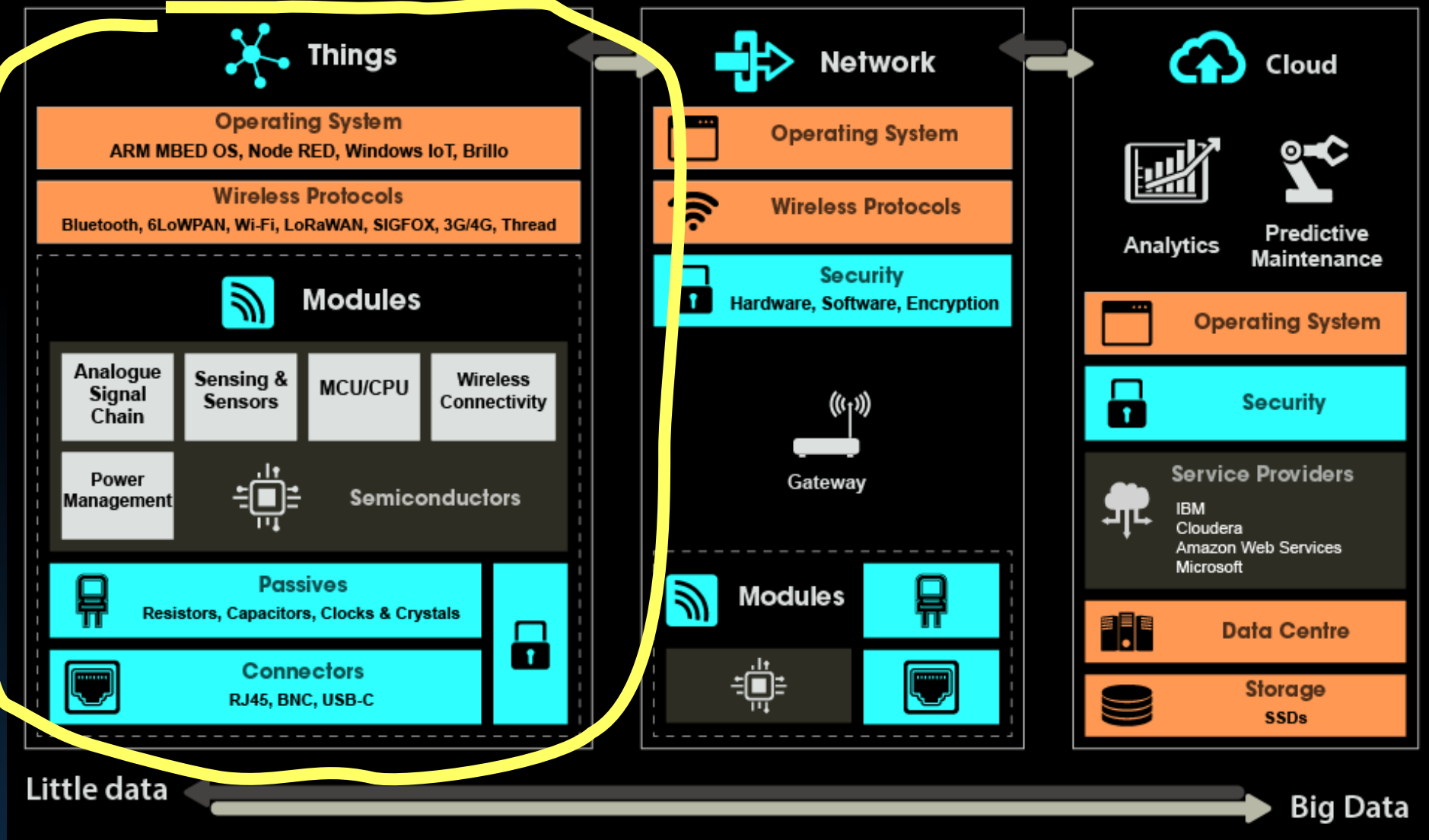
# Technology Stack





# IoT Architecture

(From a Hardware Centric Perspective)



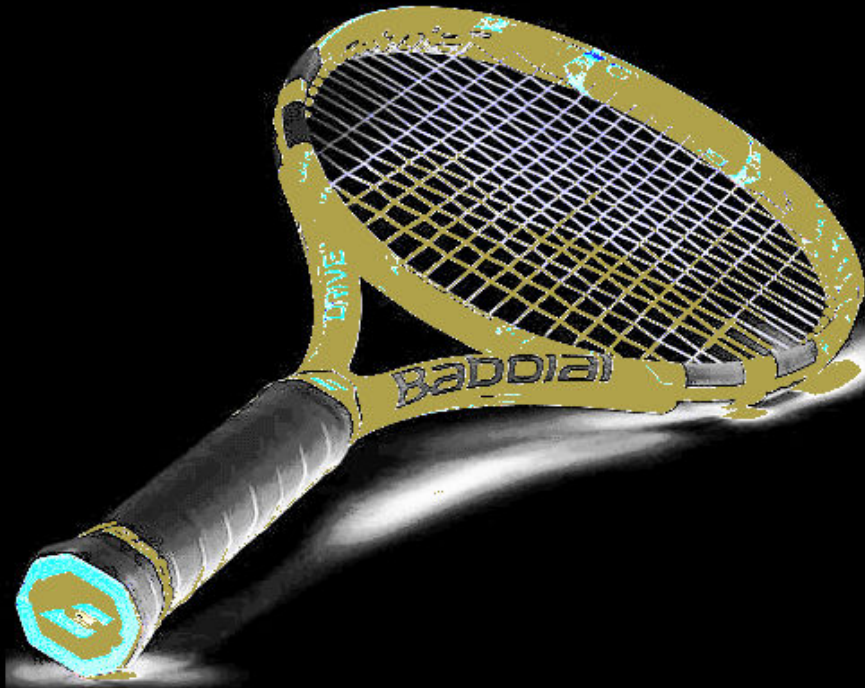
# ***Some Statistics***

**60% of IoT initiatives stall at the Proof of Concept stage**

Overall nearly three-fourths of Internet of Things initiatives are considered a failure, while a third of all projects being completed were not seen as a success

- Cisco Survey 2017

# *You have an idea.*



(images courtesy Babolat)

# *Now what?*

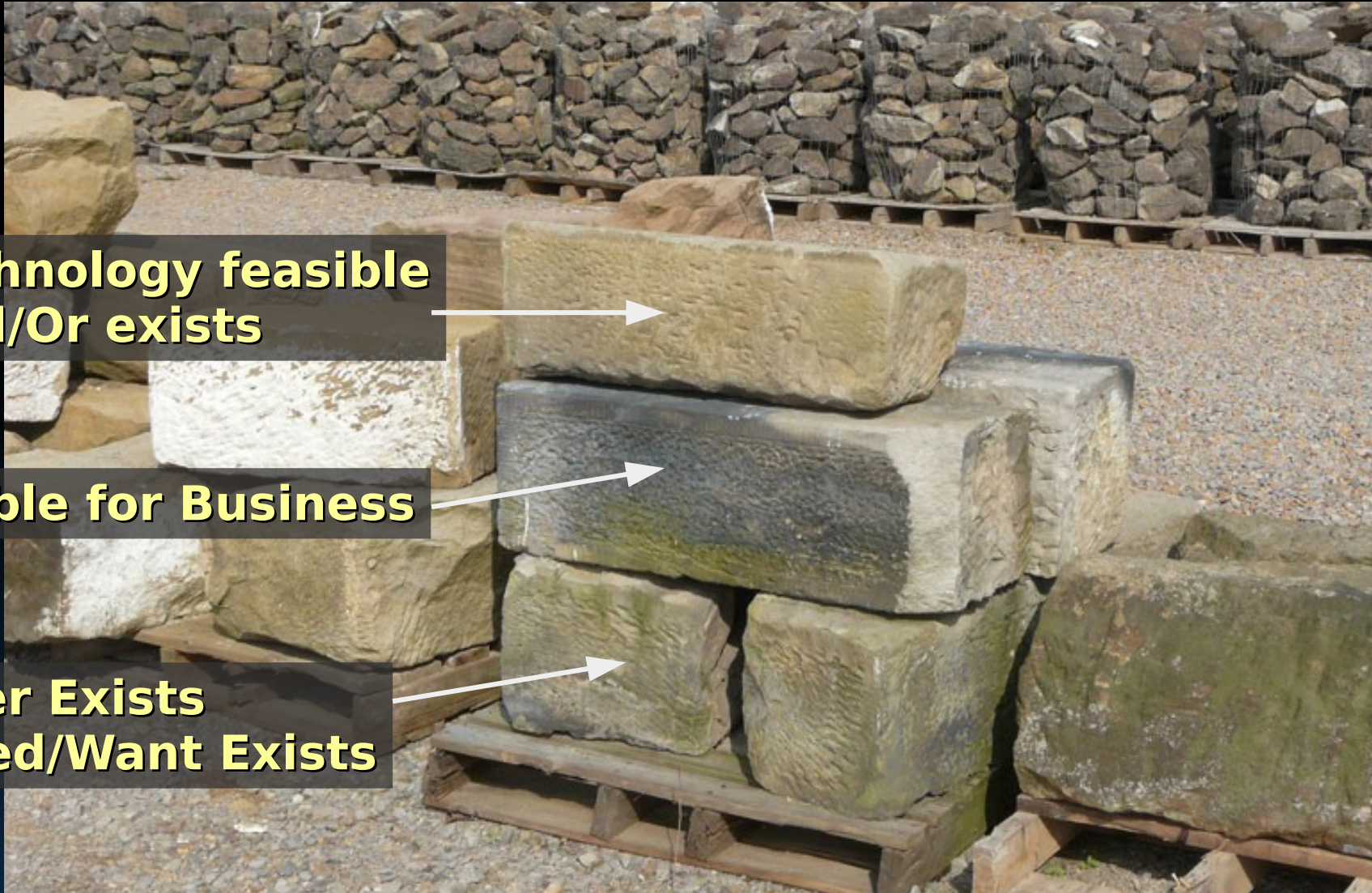


# *Foundation Stones*

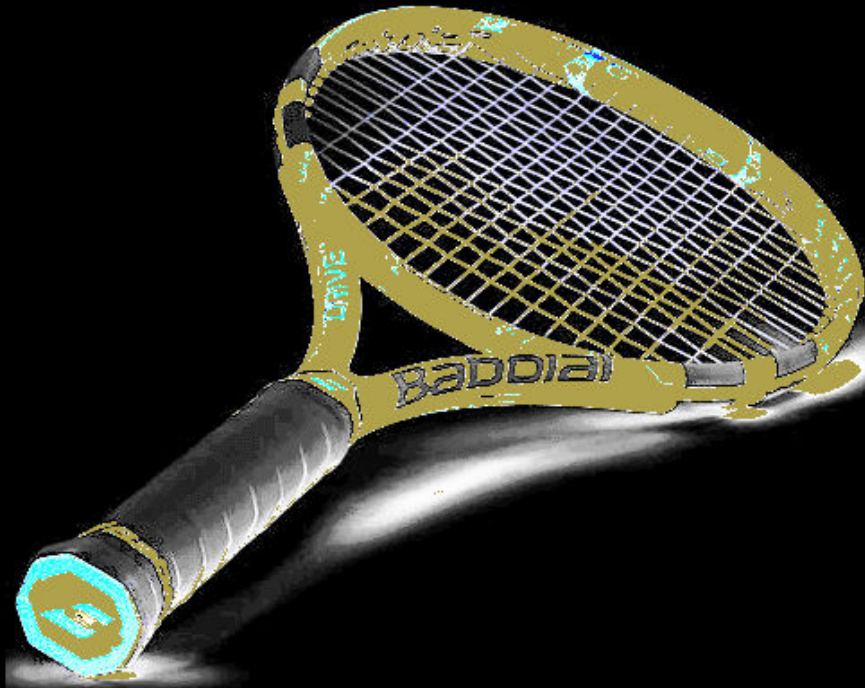
**Technology feasible  
And/Or exists**

**Viable for Business**

**User Exists  
Need/Want Exists**



# *Idea → Concept → Reality*



(images courtesy Babolat)

## *How to realize the idea?*



# *Steps*



**Concept  
&  
Design**

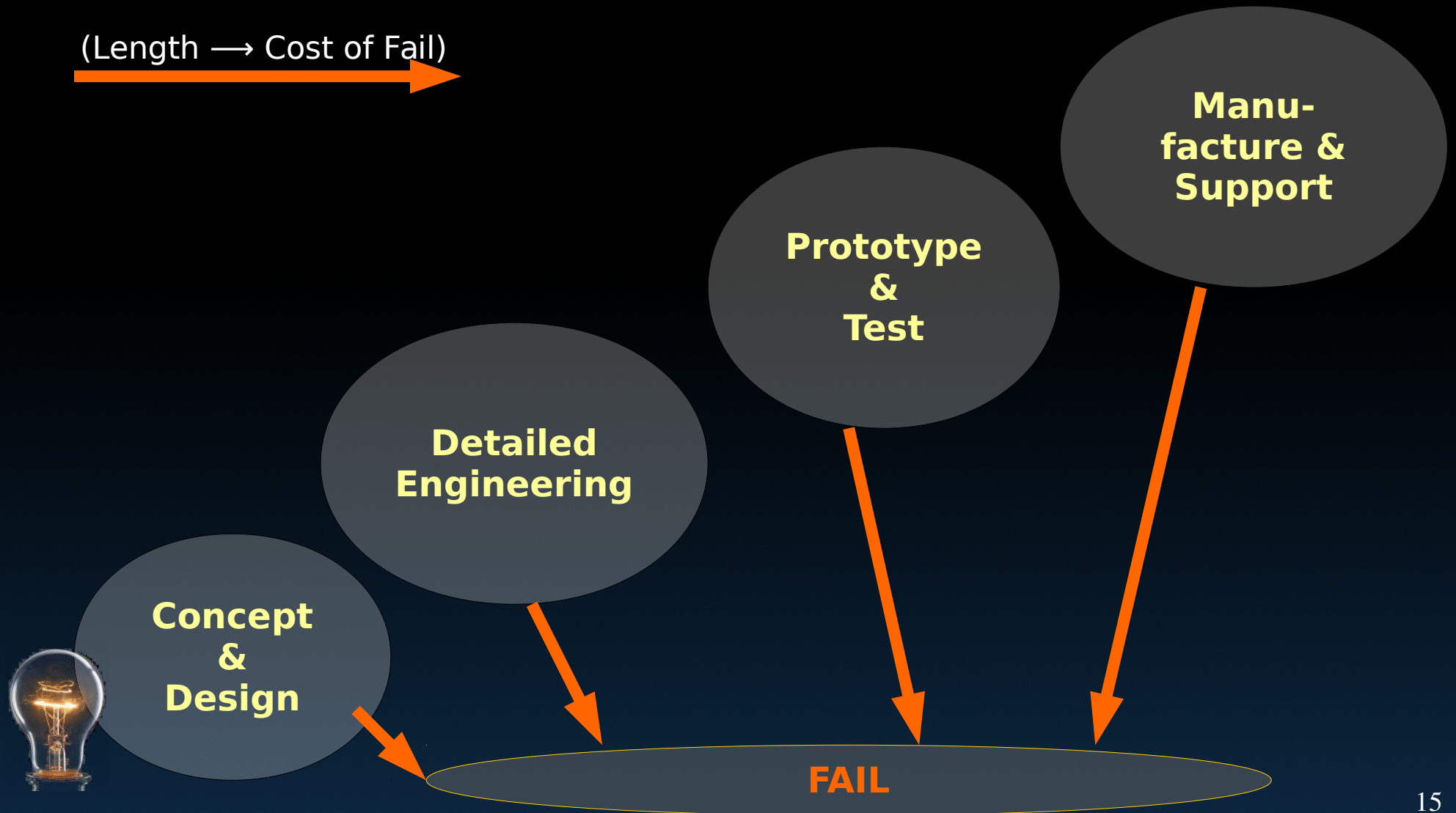
**Detailed  
Engineering**

**Prototype  
&  
Test**

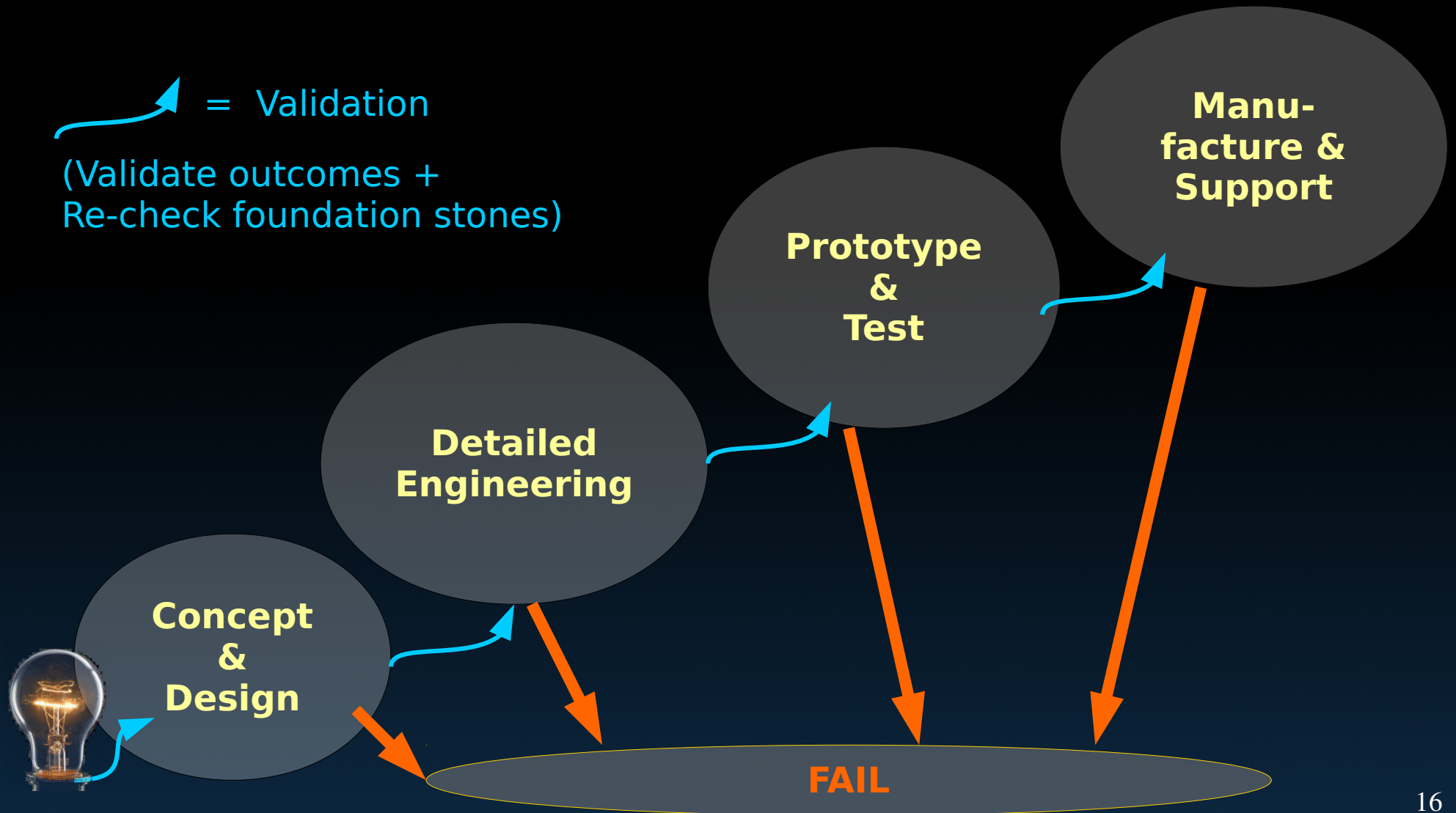
**Manu-  
facture &  
Support**

# Why “Fail Fast”?

(Length → Cost of Fail)



# Validate + “Fail Fast”



## 2. IoT Hardware Development Overall Strategy, Work Items & Steps

... Or, How to make it fly!

Overview of issues and work items in:

# ***Concept & Design***

(of your IoT Hardware)

- Hardware Form Factor  
Size, shape, weight
- Connectivity  
ZigBee? LoRa 433MHz? NB-IoT?
- Power Constraints  
Battery Life, Sleep %, Energy harvesting...
- Environmental  
Industrial? EMI? IP20? or IP69K?
- Regulatory, Legal etc  
Healthcare? Food Safety?



Overview of issues and work items in:

# ***Detailed Engineering***

- Subsystems, boundaries, interfaces
- Component Selection, Qualification
- Schematic Design, Simulation
- DFP (Design for ease of Prototyping)
- Interconnects and Harnesses
- Physical Design
  - PCB Form factors, # layers, flex or not?
  - Mech. Design, Thermal Design, Enclosures
  - Design PCBs – Layout and Route

Overview of issues and work items in:

# ***Prototyping, Testing***

- Build prototypes
  - Module-based prototyping (early stage)
  - Incremental prototyping
  - Allow h/w – s/w co-design
  - Generate early feedback
- Test
  - Isolate subsystem-wise and test
  - Integrate, assemble
  - Measure, verify design goals

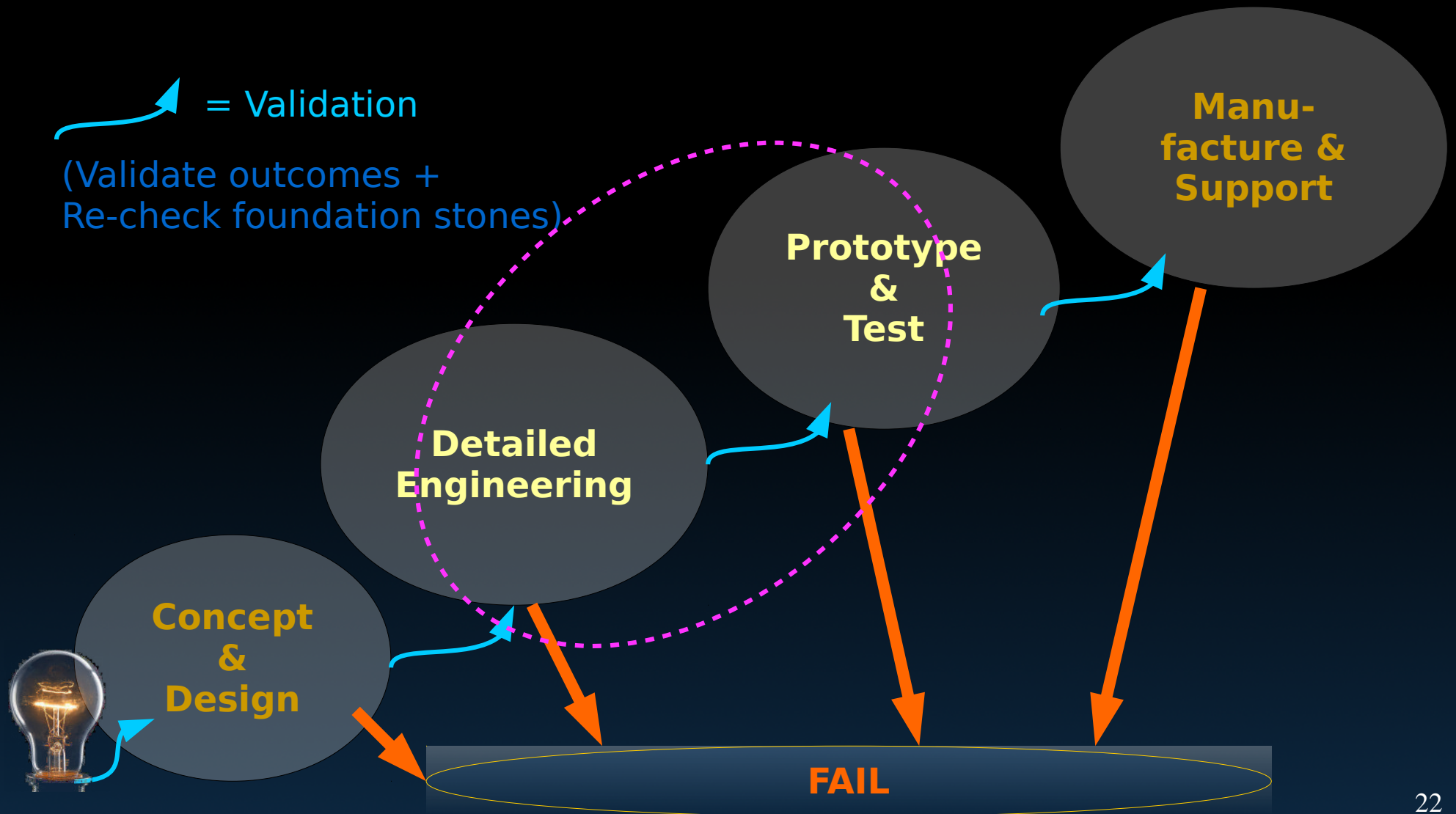
Overview of issues and work items in:

# ***Manufacturing, Support***

- DFM – Design for Manufacture
- Optimize BoM & Inventory
- Optimal process
- Modular assembly & Test
- Traceability & Tracking
- Spares & Fulfillment ...

(Insight)

# ***Proto & Test is a key activity!***



# ***Importance of P & T***

(Prototyping & Testing)

- Source of signals
  - “Fail Fast” signals
  - Directs further stages / iteration
- P & T Cycle time is crucial
  - Repeated activity
  - External Dependencies can be very critical
- Right Strategy, Tools, Methods!



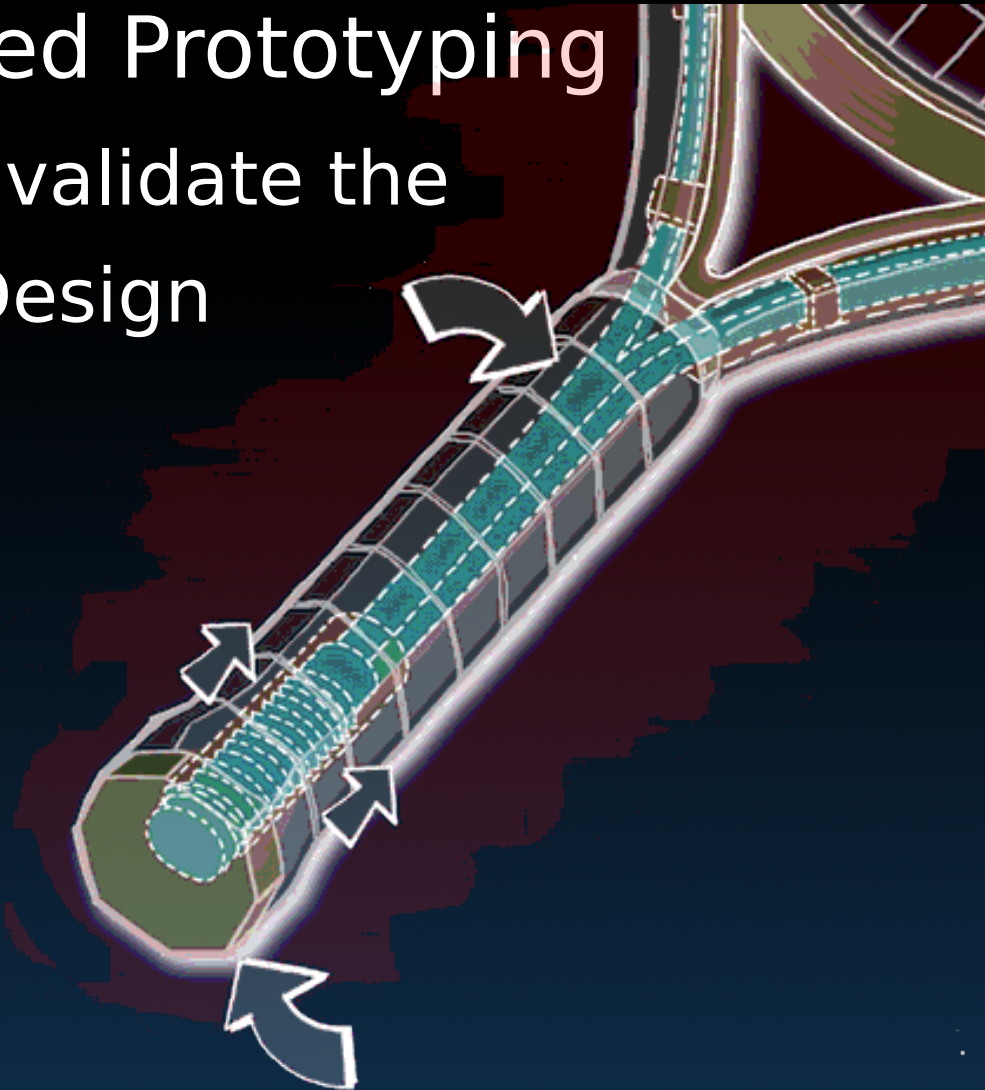
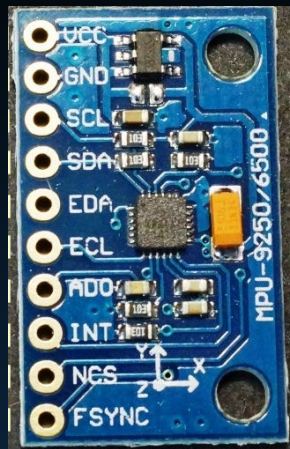
# ***Start with DFP***

(Design For ease of Prototyping)

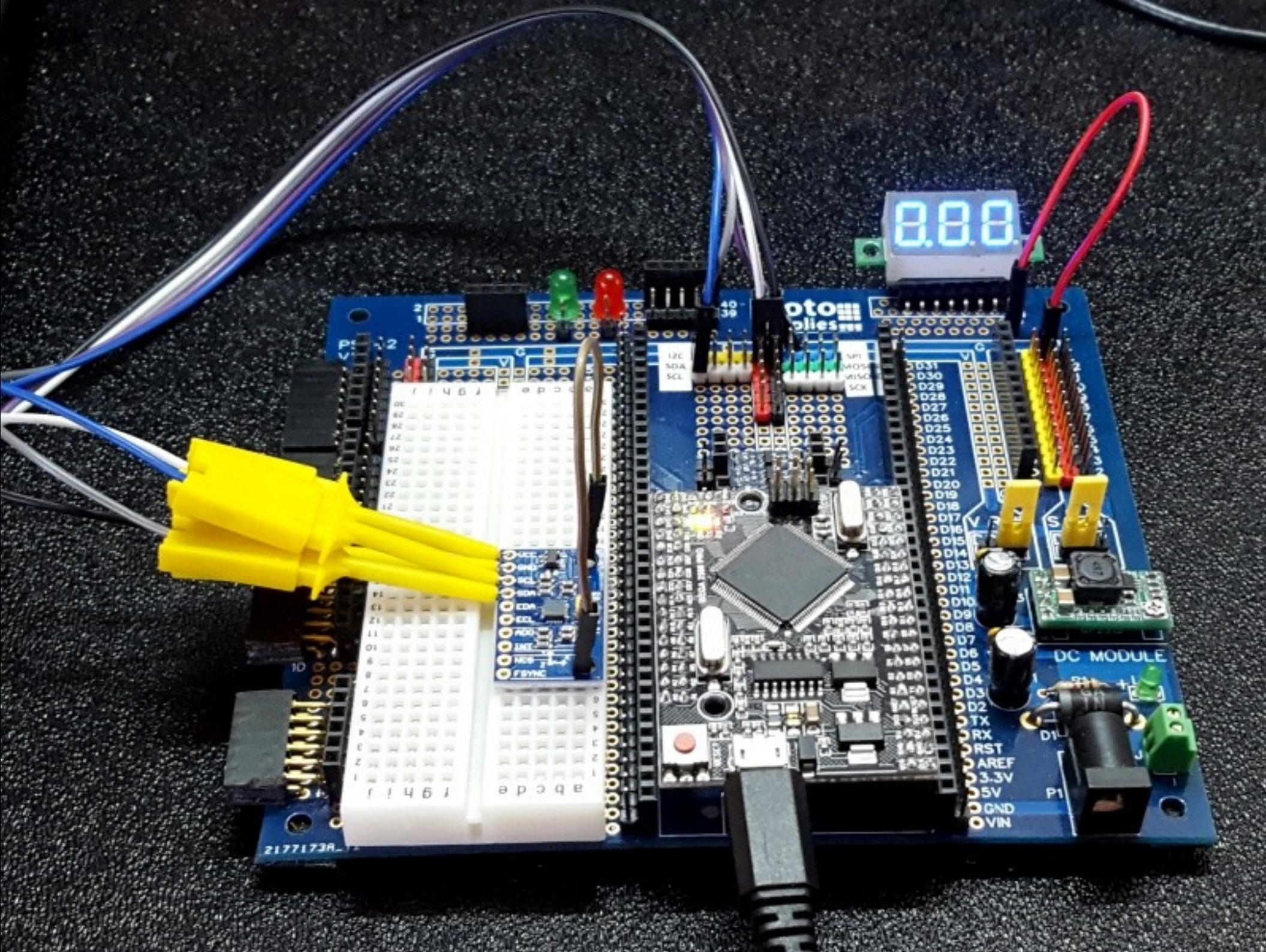
- Design for easy incremental prototyping
  - Module based prototyping
  - Use DFP tips for your SMT PCB protos
    - Refer to IEW2019 presentation :)
- Design for Testability (DFT)
  - Test points, injection points, JTAG etc

# Prototyping Strategy

- 1. Module Based Prototyping
  - To partially validate the Concept / Design









# ***Prototyping Strategy***

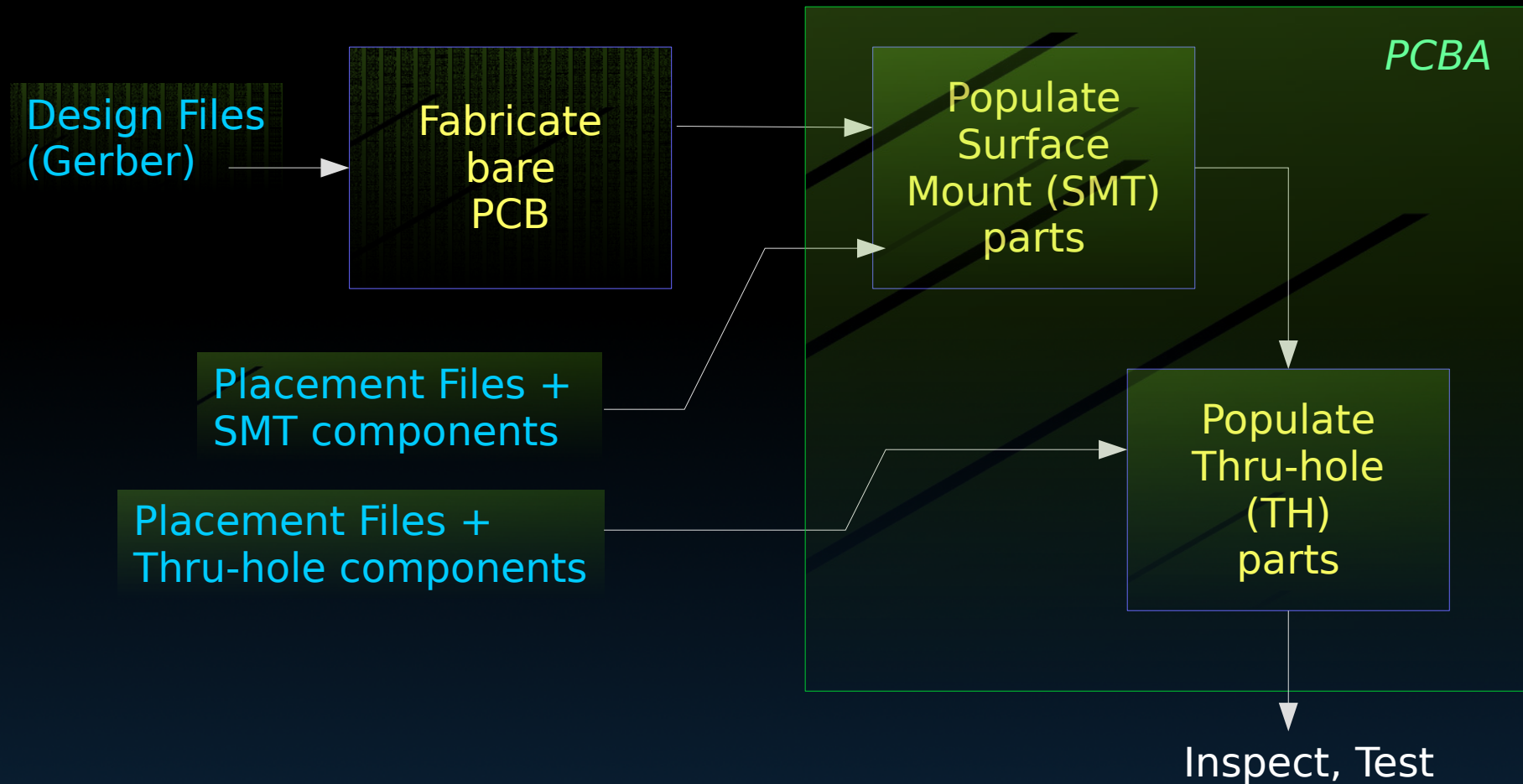
- 2. Product-intent Prototyping
  - To validate outputs of Detailed Engg.
  - Allow incremental (subsystem-wise) P & T
  - To allow software design to start (h/w-s/w codesign)
  - Run Tests & Measurements
  - To (eventually) prepare for Certifications & Manufacturing
  - Under “nearly-there” product conditions

# ***DFP Tips Overview***

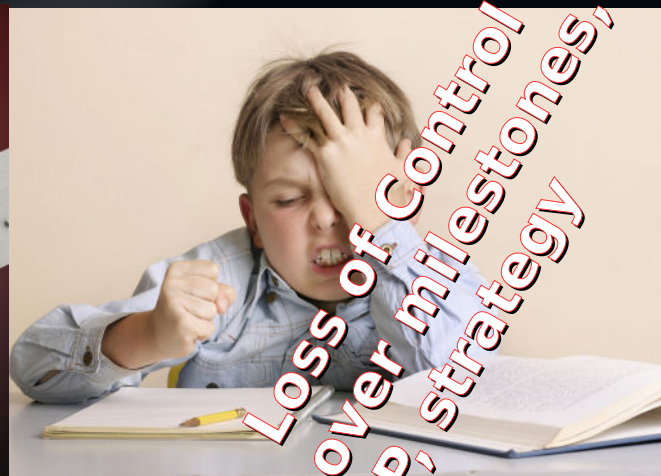
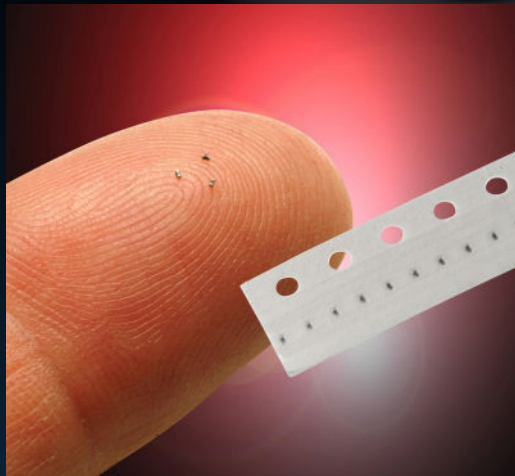
- Insert Test points
- Use 0-R's to isolate ckts, subsystems
- Use easy-to-proto parts / footprints
- Use 0-R's for trial configurations/options
- Accessibility for rework
- ...etc [Refer to IEW2019 talk]



# PCB based Prototyping



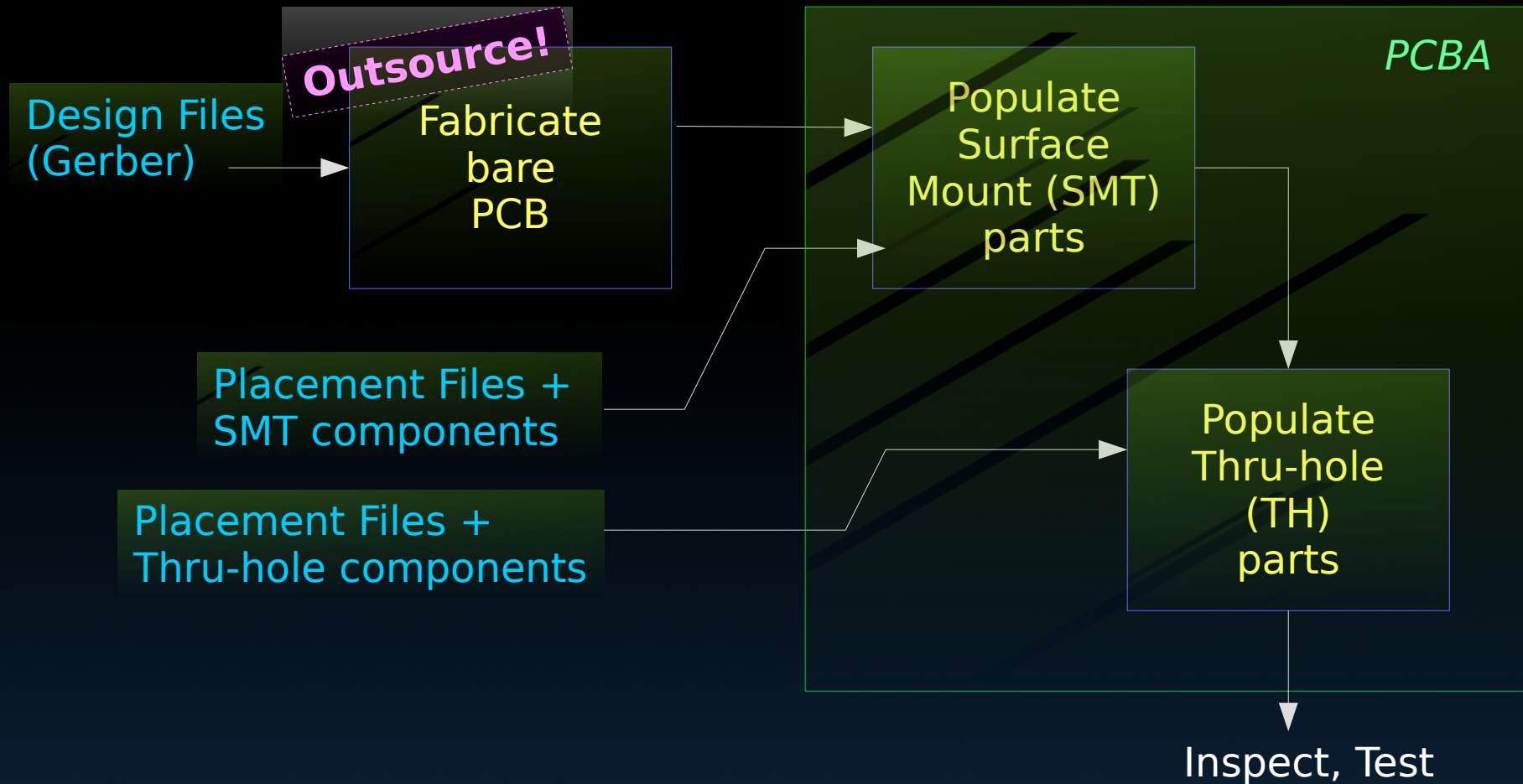
# Challenges in Product-Intent Prototyping



# *Outsourcing ?*

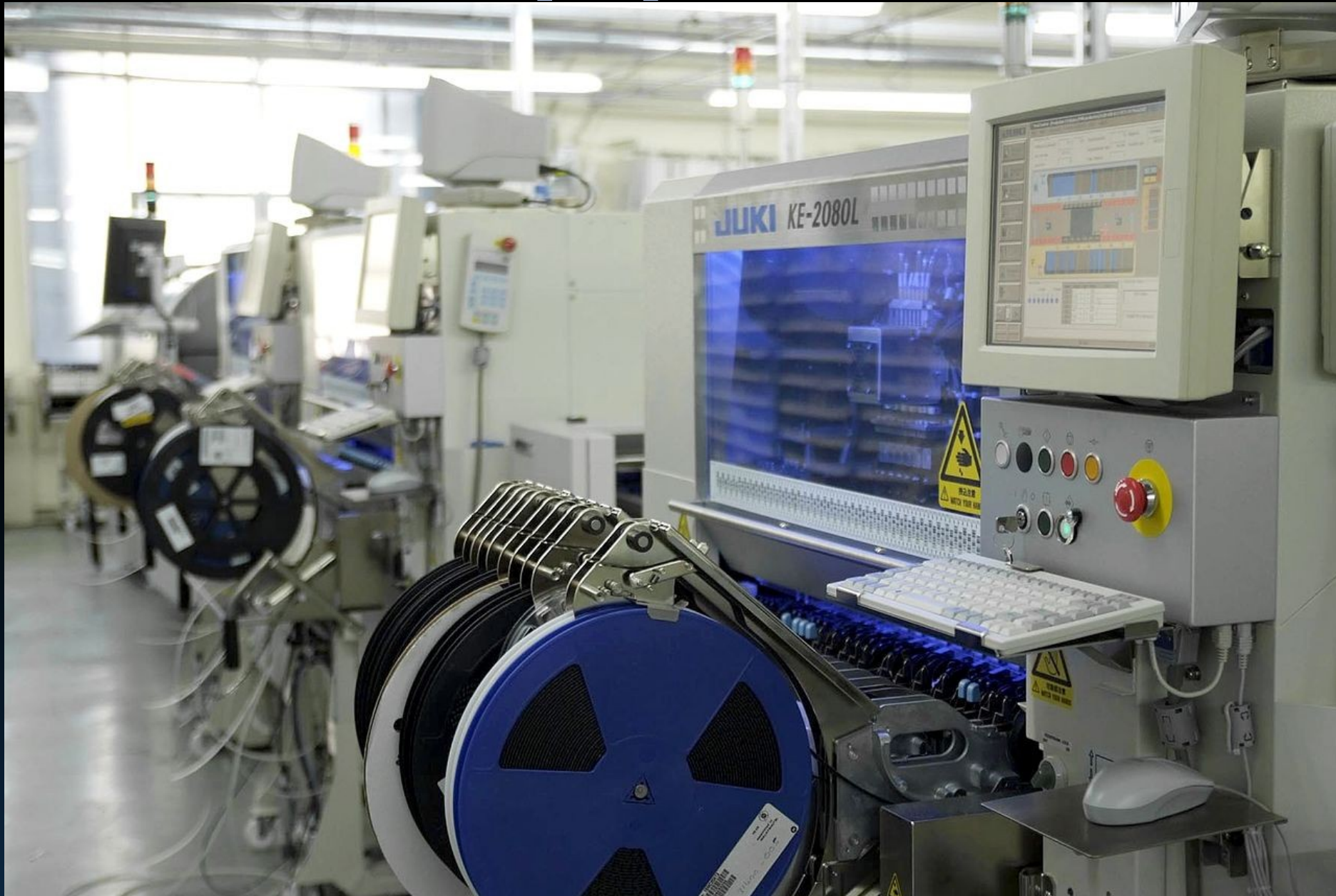
- Negatives of Outsourced Prototyping
  - Increased cycle time, loss of control
  - Puts Time-to-Market under risk
  - Potential Intellectual Property risks
  - Parts overages/wastage
  - Kills incremental prototyping strategy
  - Impedes h/w – s/w codesign strategy

# PCB based Prototyping

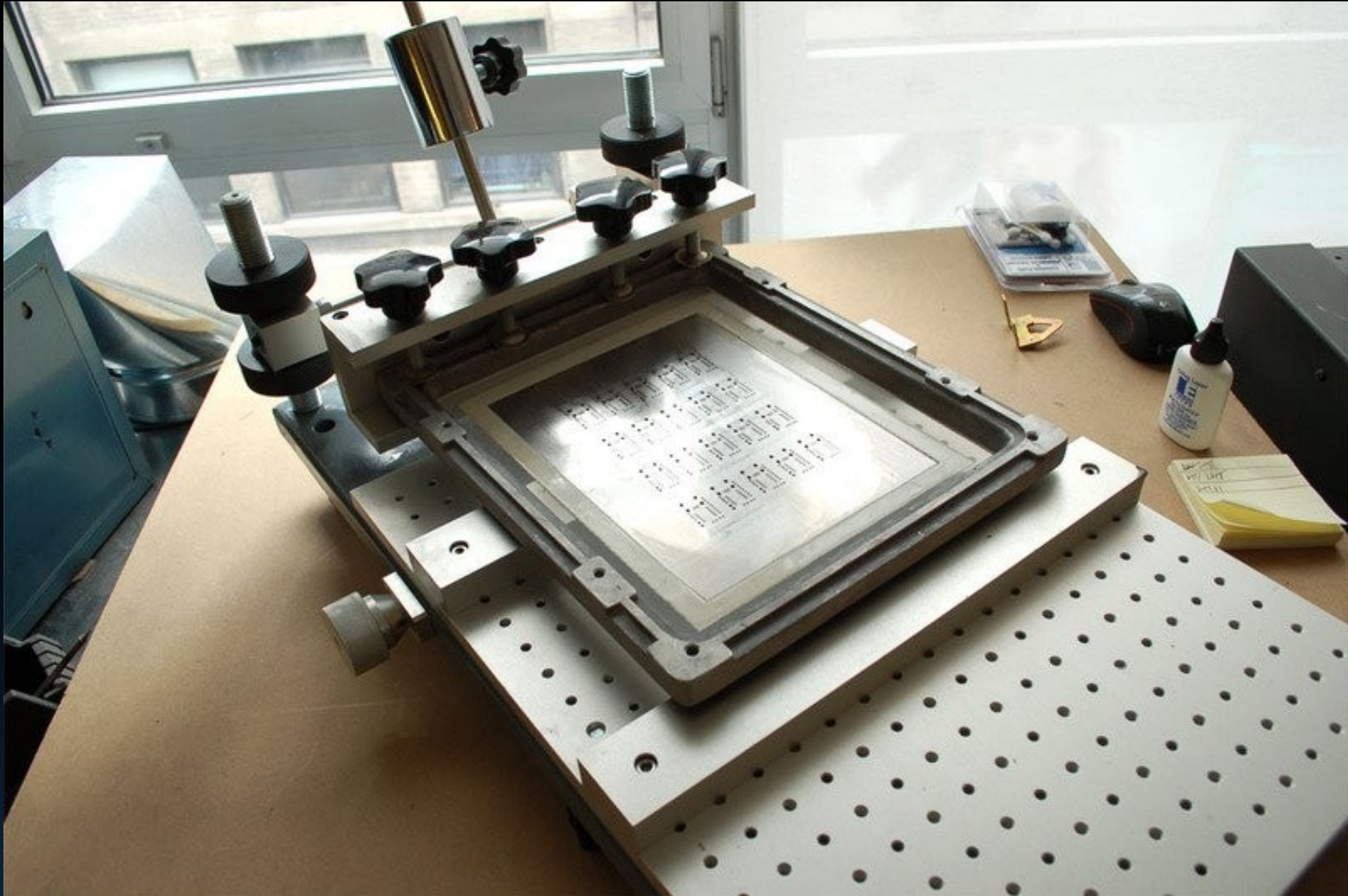




# PCBA Equipment





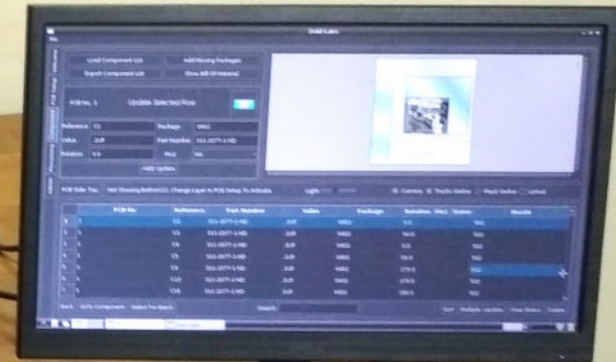
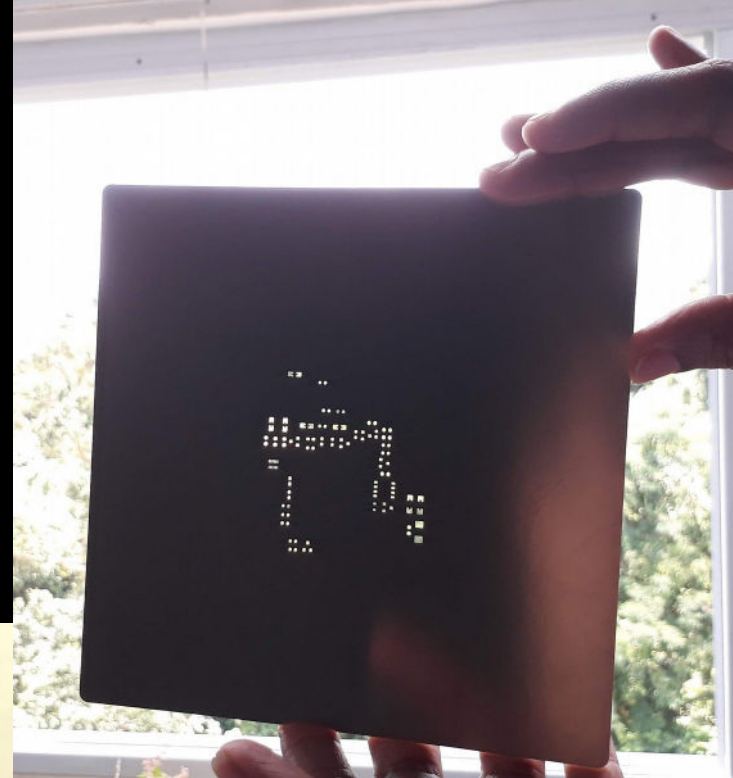




Prototyping on your Desktop  
is **no longer a dream.**

Cut Stencil →

PlacerBot™



# More DFP / DFM tips

- 1. Don't "Live Dangerously!"

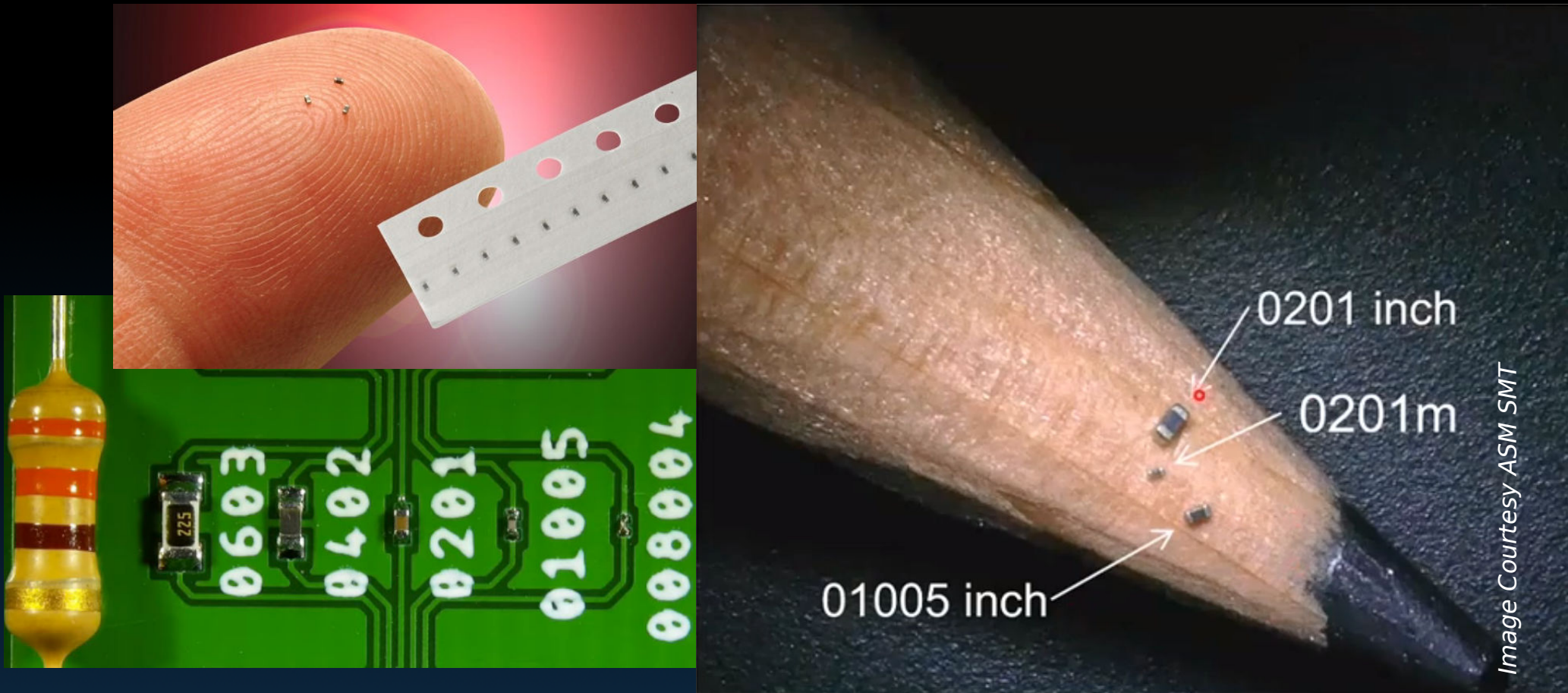
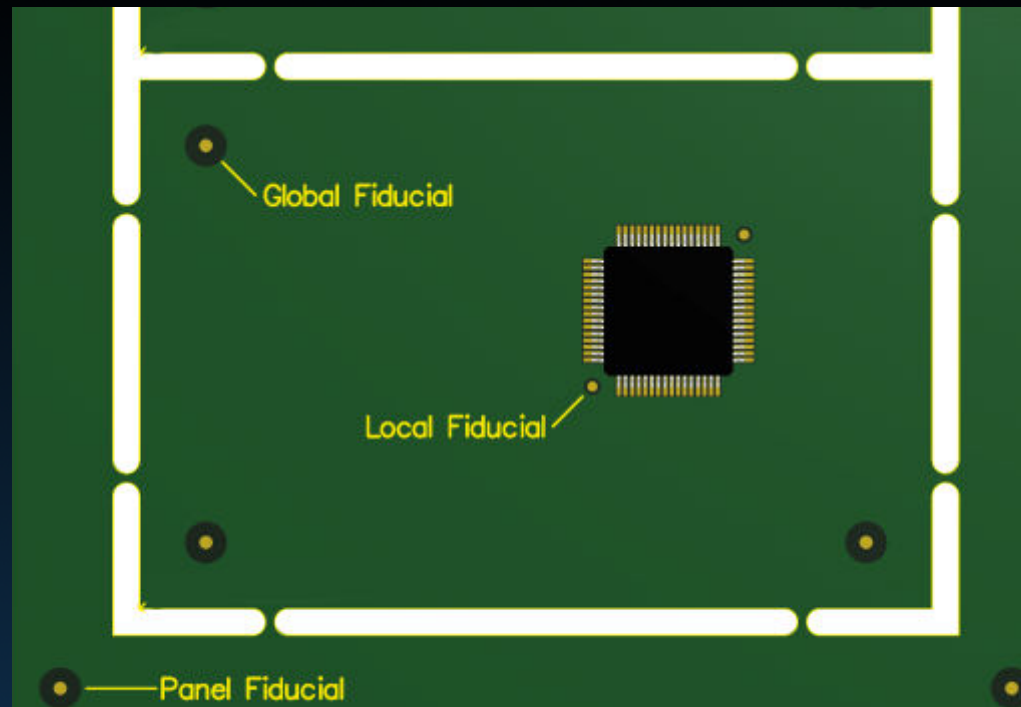


Image Courtesy ASM SMT

# More DFP / DFM tips

- 2. Use Fiducials
  - Global Fiducials (nice to have 3)
  - Local Fids near large fine pitch ICs
  - Export Fids also to Placement File.



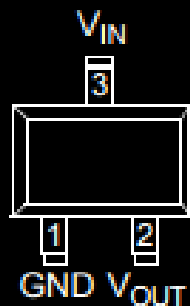


# More DFP / DFM tips

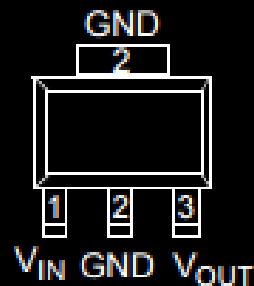
- 3. Ensure “standard” Pin 1 positions
  - use footprints with “standard” rotation angles

## Package Types – MCP1754S

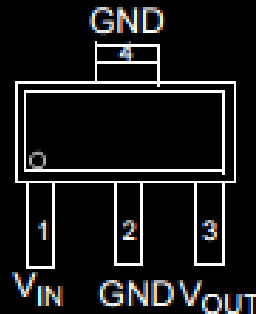
3-Pin SOT-23A



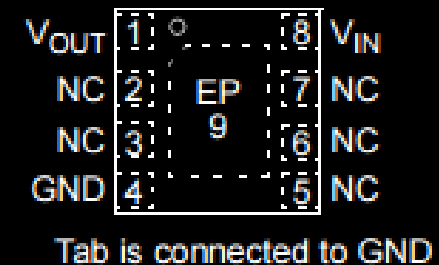
3-Pin SOT-89



SOT-223-3



8-Lead 2X3 DFN(\*)



(Note: The 3-lead SOT-223 (DB) is not a standard package for output voltages below 3.0V)

\* Includes Exposed Thermal Pad (EP); see Table 3-2.

## *More DFP / DFM tips*

- 4. Use Part Numbers (and/or other unique ID like HPN – House P/N or equivt.)
- 5. Take Component Management seriously!



# *Equipment / Process Capability for Proto*

- Should work with multi-layer PCBs
- -do- with cut stencils & T3/T4 paste (long life paste saves you grief)
- Passives min size 0402, 0201 desirable
- Fine pitch ICs
- Accept flexible feed volumes (cut tape, IC trays; not big reels!)
- Visual Feedback, friendly GUI, batch & ad-hoc modes
- Modest PCB sizes, reasonable speed
- Assistance in component management



# ***Proto & Test is key***

- To tame overall dev cycle time
- To be able to implement the optimum hardware-software codesign strategy
- Thereby Time to Market
- ... and IoT success

# *Summary*

- Many IoT projects fail; Fail-Fast is good
- Proper strategy and execution are important
- Proto & Test is key in IoT h/w dev
  - Control over P&T is crucial
  - Deploy the Right Equipment, Process and Methods that support your strategy